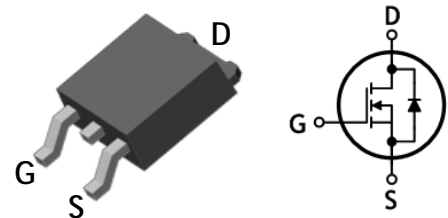


## N-Channel Super Junction MOSFET

### Features

- Drain-Source voltage:  $V_{DS}=650V$  (@ $T_J=150^{\circ}C$ )
- Low drain-source On resistance:  $R_{DS(on)}=0.3\Omega$  (Typ.)
- Ultra low gate charge:  $Q_g=23nC$  (Typ.)
- RoHS compliant device
- 100% avalanche tested

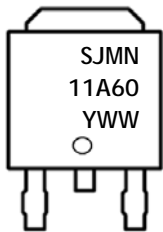


### Ordering Information

Part Number	Marking	Package
SJMN11A60D	SJMN11A60	TO-252

TO-252

### Marking Information



Column 1, 2: Device Code  
 Column 3: Production Information  
 e.g.) YWW  
 -. Y: Year Code  
 -. WW : Week Code

### Absolute maximum ratings ( $T_C=25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Rating	Unit	
Drain-source voltage	$V_{DSS}$	600	V	
Gate-source voltage	$V_{GSS}$	$\pm 30$	V	
Drain current (DC) <sup>(Note 1)</sup>	$I_D$	$T_C=25^{\circ}C$	11	A
		$T_C=100^{\circ}C$	7	A
Drain current (Pulsed) <sup>(Note 1)</sup>	$I_{DM}$	30	A	
Single pulsed avalanche energy <sup>(Note 2)</sup>	$E_{AS}$	350	mJ	
Repetitive avalanche current <sup>(Note 1)</sup>	$I_{AR}$	11	A	
Repetitive avalanche energy <sup>(Note 1)</sup>	$E_{AR}$	12.5	mJ	
Power dissipation	$P_D$	83	W	
Junction temperature	$T_J$	150	$^{\circ}C$	
Storage temperature range	$T_{stg}$	-55-150	$^{\circ}C$	

\* Limited only maximum junction temperature

## Thermal Characteristics

Characteristic	Symbol	Rating	Unit
Thermal resistance, junction to case	$R_{th(j-c)}$	Max. 1.5	°C/W
Thermal resistance, junction to ambient	$R_{th(j-a)}$	Max. 62	

Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	$BV_{DSS}$	$I_D=250\mu\text{A}$ , $V_{GS}=0\text{V}$	600	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu\text{A}$ , $V_{DS}=V_{GS}$	2	-	5	V
Drain-source cut-off current	$I_{DSS}$	$V_{DS}=600\text{V}$ , $V_{GS}=0\text{V}$	-	-	1	$\mu\text{A}$
		$V_{DS}=480\text{V}$ , $T_J=125^\circ\text{C}$	-	-	10	$\mu\text{A}$
Gate leakage current	$I_{GSS}$	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 30\text{V}$	-	-	$\pm 100$	nA
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$ , $I_D=5.5\text{A}$	-	0.3	0.35	$\Omega$
Gate resistance	$R_G$	$f=1\text{MHz}$ , Open drain	-	1.0	-	$\Omega$
Input capacitance	$C_{iss}$	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	-	1050	-	pF
Output capacitance	$C_{oss}$		-	660	-	
Reverse transfer capacitance	$C_{rss}$		-	9	-	
Turn-on delay time (Note 3)	$t_{d(on)}$	$V_{DD}=380\text{V}$ , $I_D=5.5\text{A}$ , $R_G=4.7\Omega$ , $V_{GS}=10\text{V}$	-	16	-	ns
Rise time (Note 3)	$t_r$		-	14	-	
Turn-off delay time (Note 3)	$t_{d(off)}$		-	40	-	
Fall time (Note 3)	$t_f$		-	5	-	
Total gate charge (Note 4)	$Q_g$	$V_{DS}=480\text{V}$ , $V_{GS}=10\text{V}$ , $I_D=5.5\text{A}$	-	23	-	nC
Gate-source charge (Note 4)	$Q_{gs}$		-	7	-	
Gate-drain charge (Note 4)	$Q_{gd}$		-	7	-	

Source-Drain Diode Ratings and Characteristics ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Source current (DC)	$I_S$	Integral reverse diode in the MOSFET	-	-	11	A
Source current (Pulsed)	$I_{SM}$		-	-	30	A
Forward voltage	$V_{SD}$	$V_{GS}=0\text{V}$ , $I_S=5.5\text{A}$	-	-	1.4	V
Reverse recovery time (Note 3,4)	$t_{rr}$	$I_S=11\text{A}$ , $V_R=50\text{V}$ , $di_S/dt=100\text{A}/\mu\text{s}$	-	439	-	ns
Reverse recovery charge (Note 3,4)	$Q_{rr}$		-	3.6	-	$\mu\text{C}$

## Note:

1. Calculated continuous current based on maximum allowable junction temperature
2.  $L=52\text{mH}$ ,  $I_{AS}=3.5\text{A}$ ,  $V_{DD}=60\text{V}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3. Guaranteed by design, not subject to production testing
4. Pulse test: Pulse width $\leq 300\mu\text{s}$ , Duty cycle $\leq 2\%$

## Typical Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

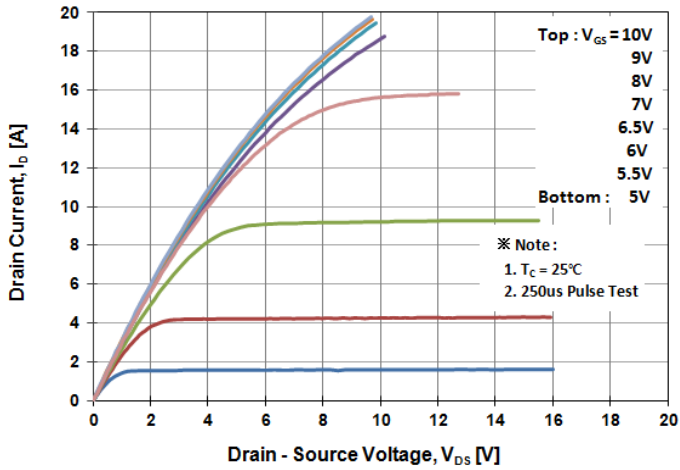


Fig. 2 Typical Transfer Characteristics

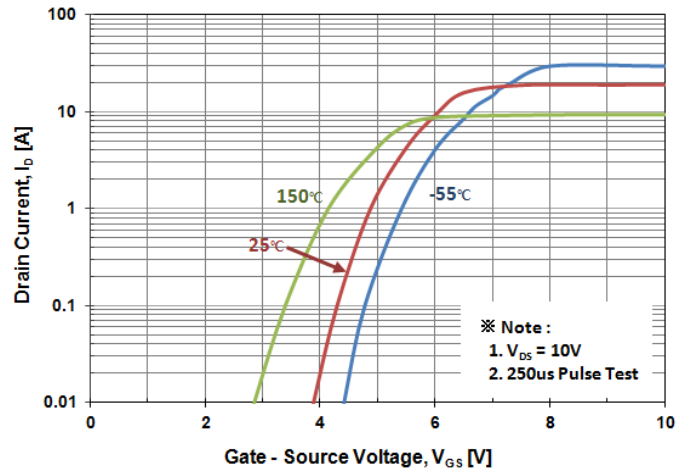


Fig. 3 On-Resistance Variation with Drain Current and Gate Voltage

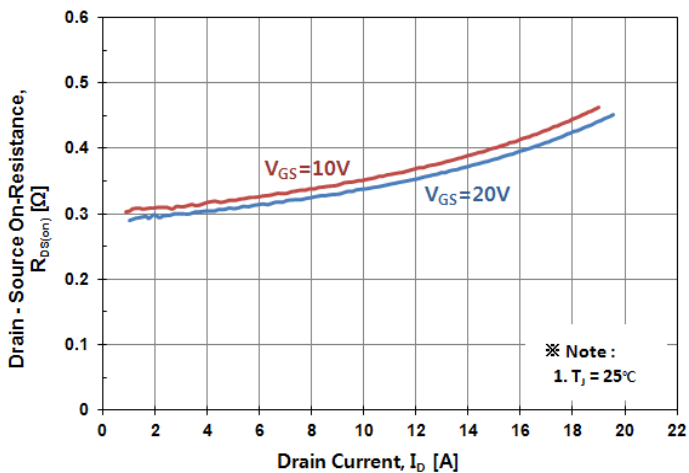


Fig. 4 Body Diode Forward Voltage Variation with Source Current

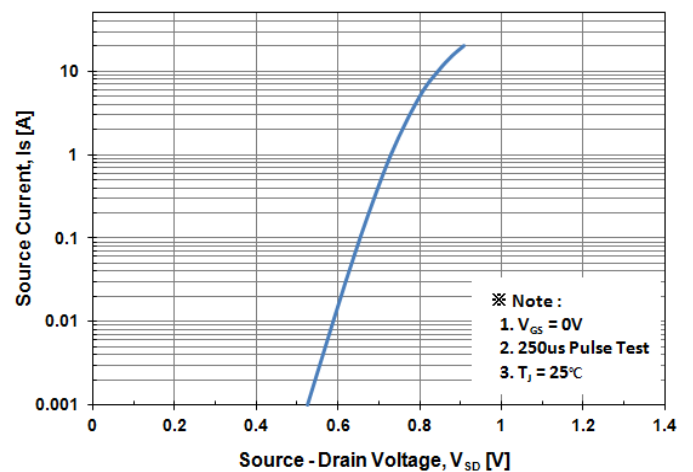


Fig. 5 Typical Capacitance Characteristics

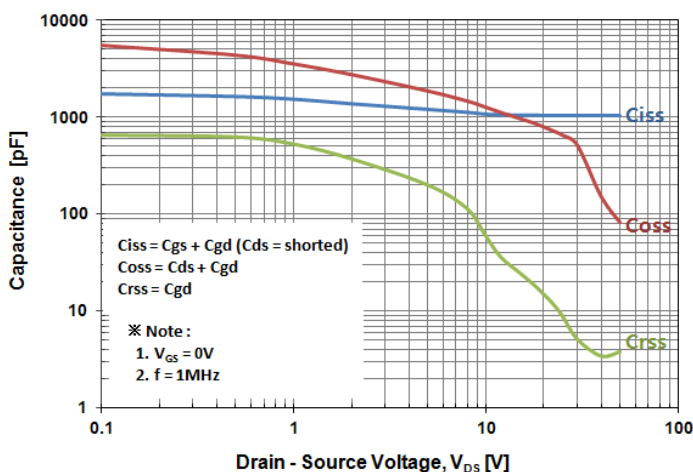


Fig. 6 Typical Total Gate Charge Characteristics

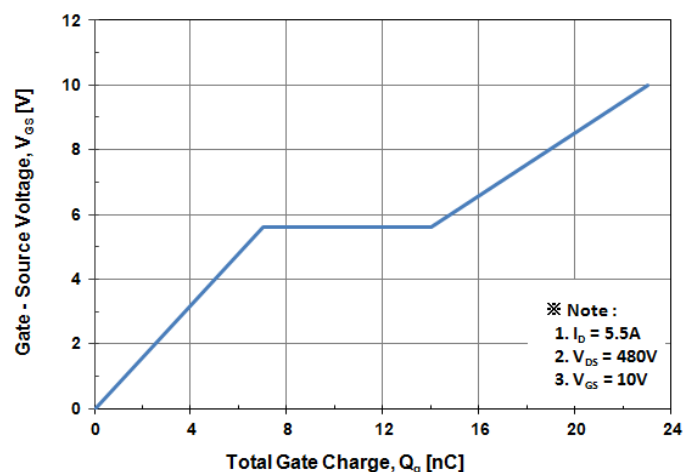


Fig. 7 Breakdown Voltage Variation vs. Temperature

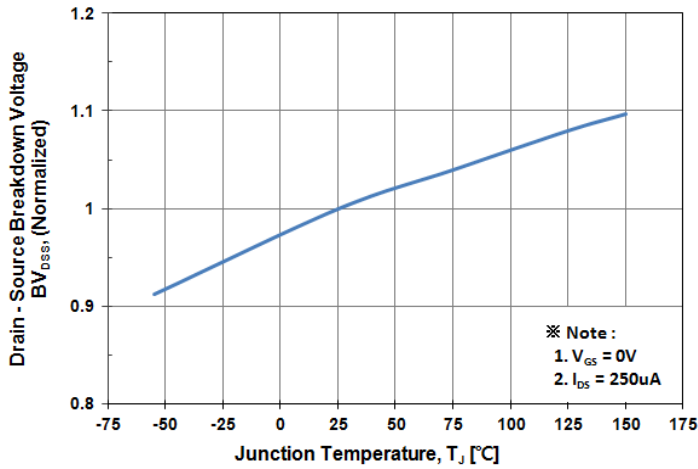


Fig. 8 On-Resistance Variation vs. Temperature

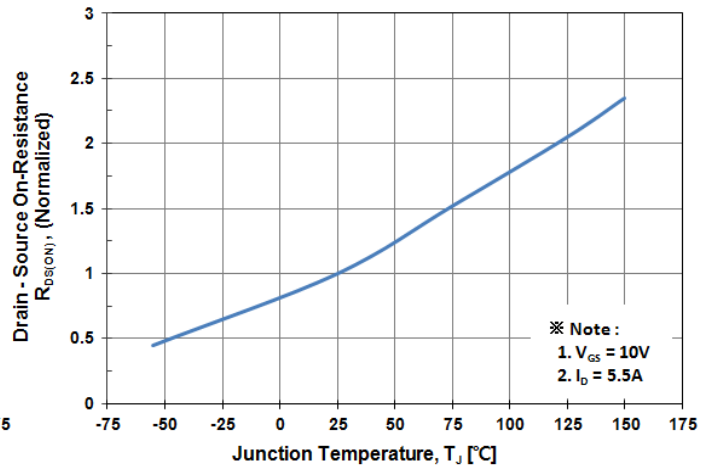


Fig. 9 Maximum Drain Current vs. Case Temperature

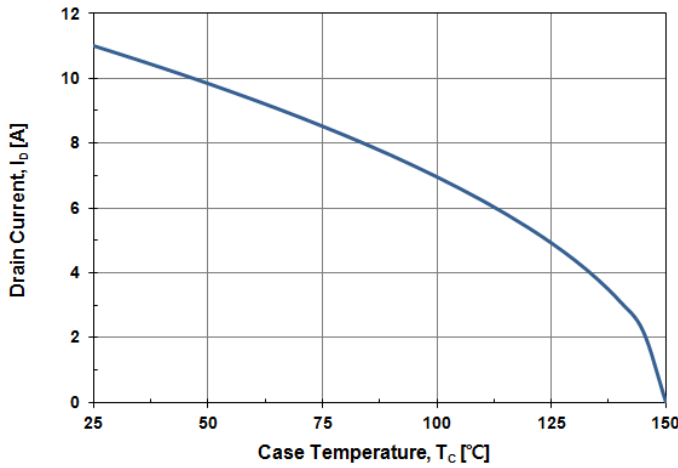


Fig. 10 Maximum Safe Operating Area

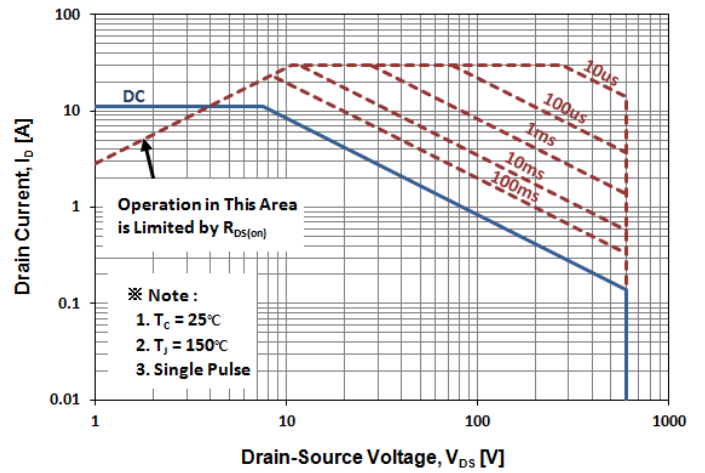


Fig. 11 Transient Thermal Impedance

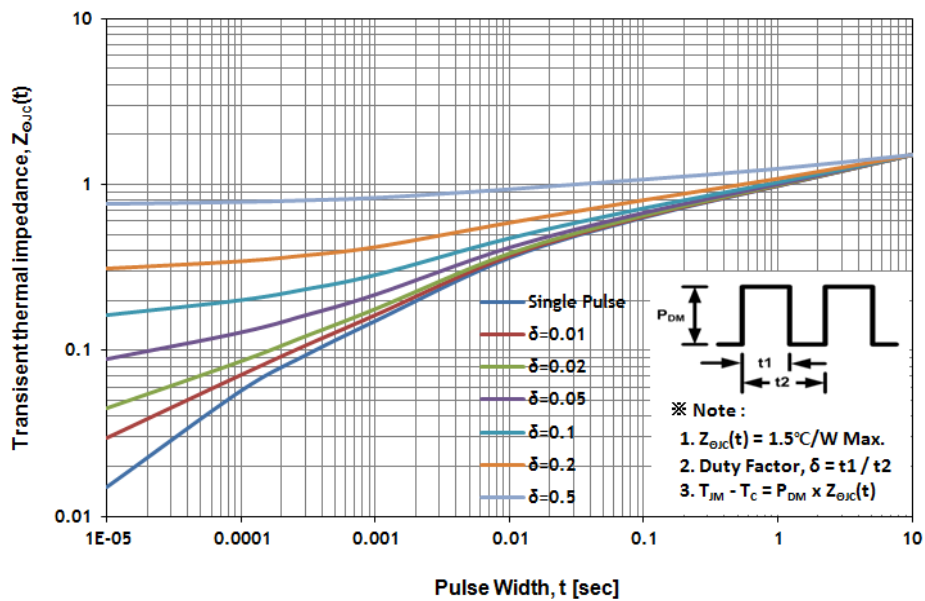


Fig. 12 Gate Charge Test Circuit & Waveform

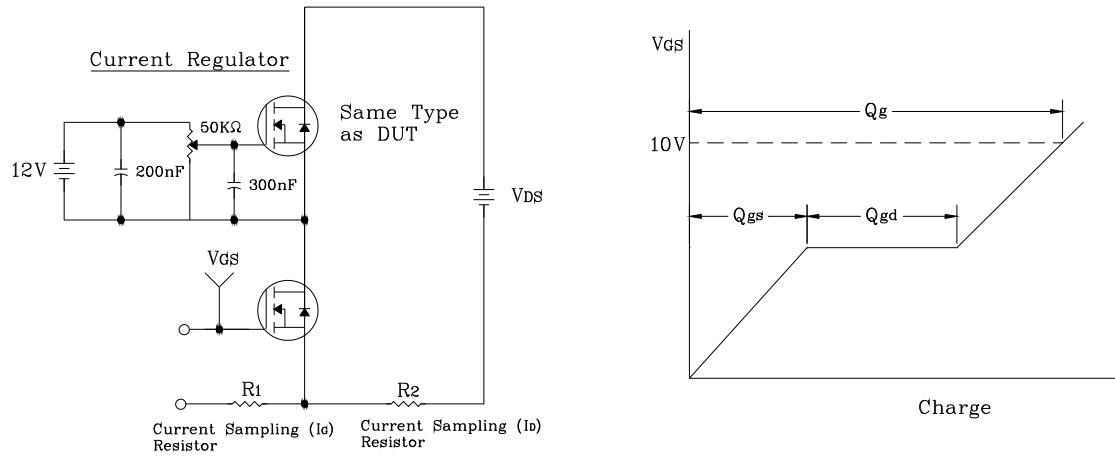


Fig. 13 Resistive Switching Test Circuit & Waveform

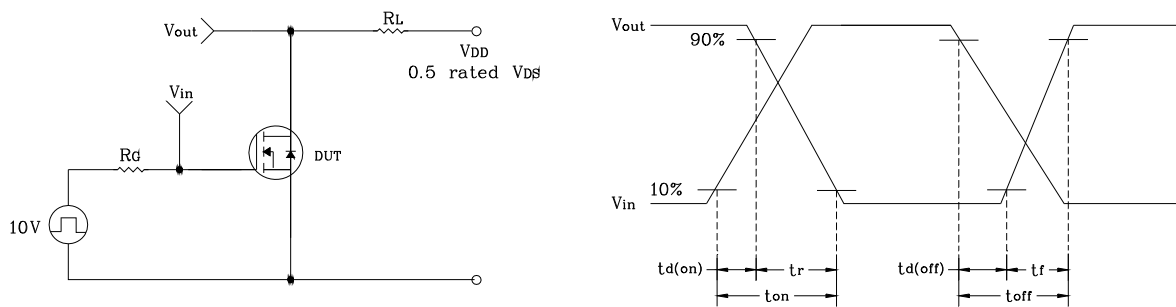


Fig. 14 E<sub>AS</sub> Test Circuit & Waveform

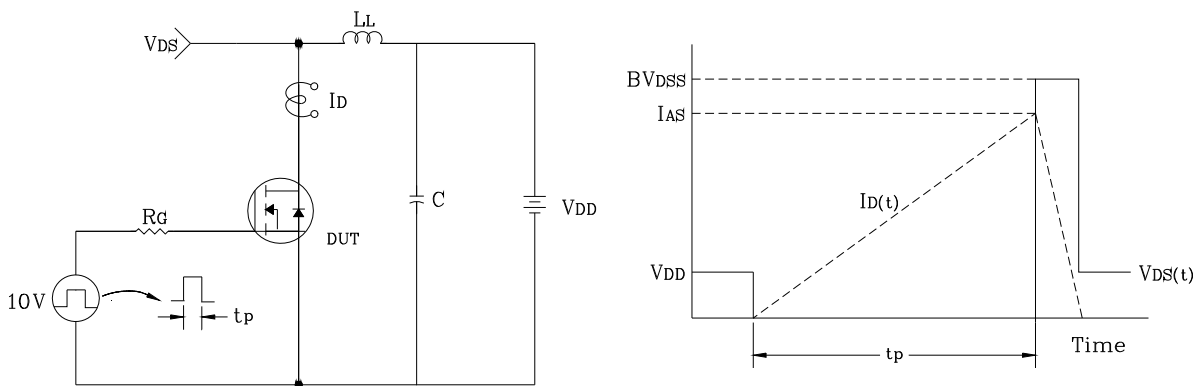
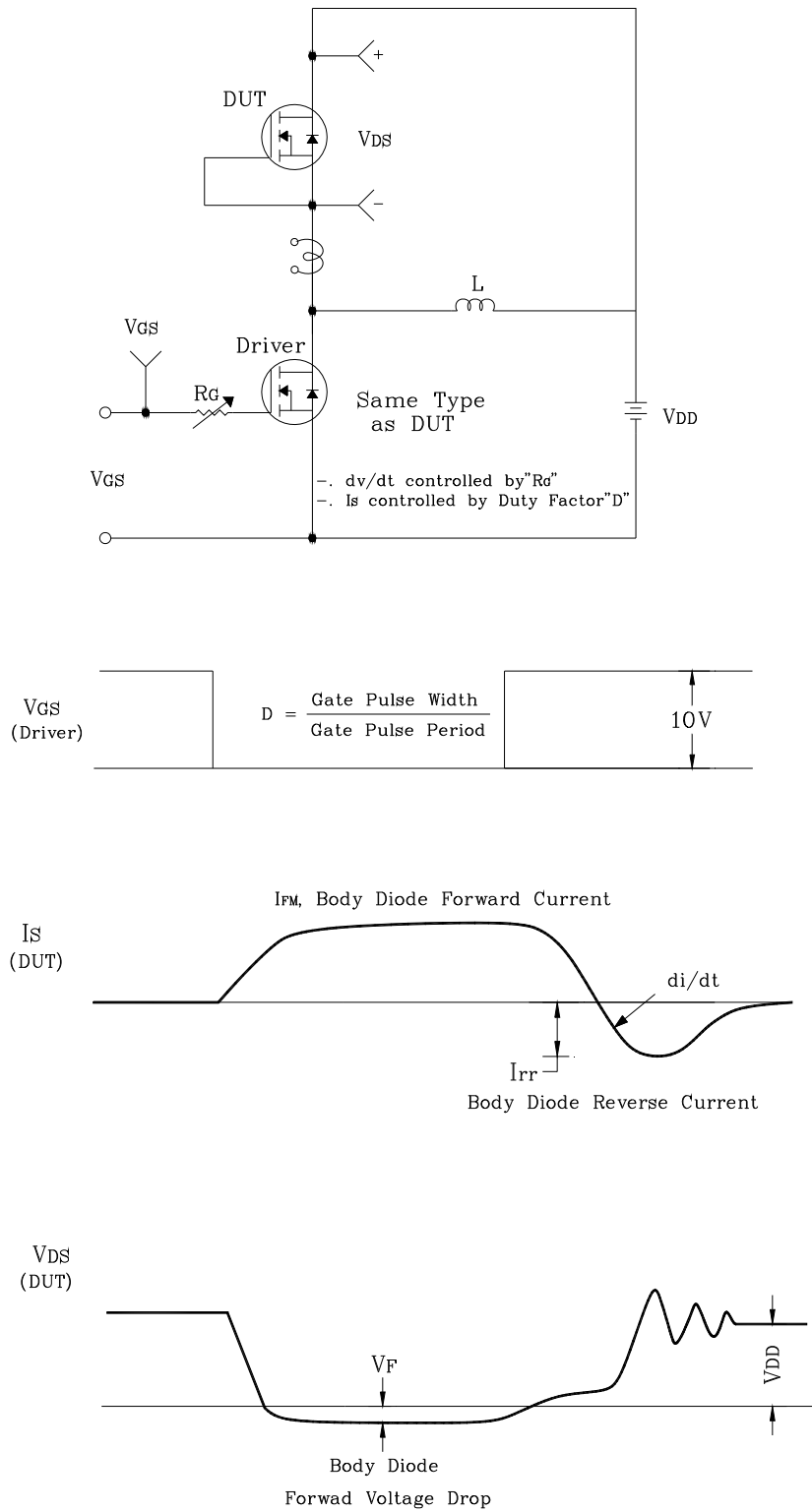
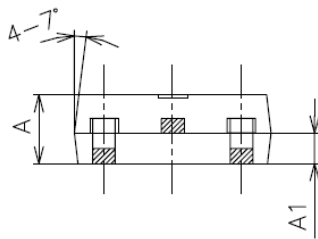
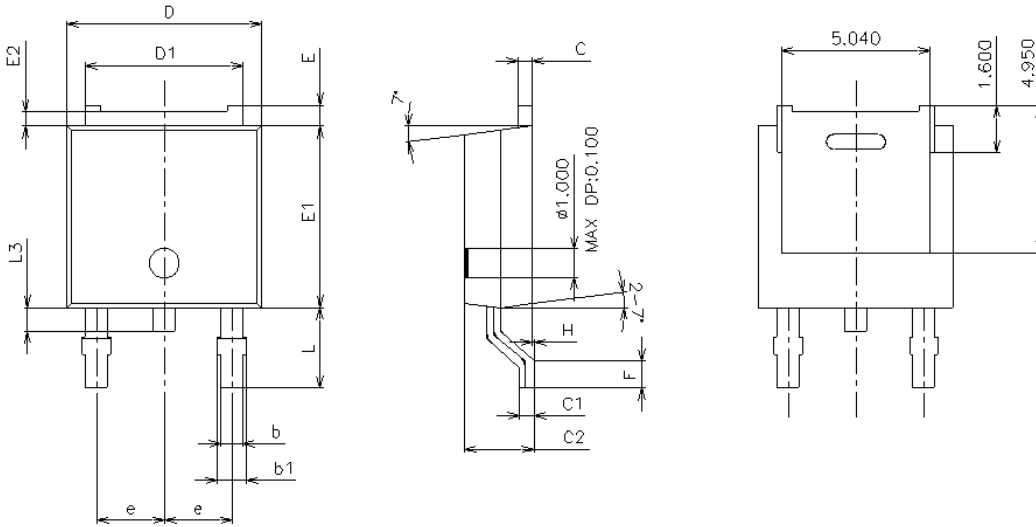


Fig. 15 Diode Reverse Recovery Time Test Circuit & Waveform

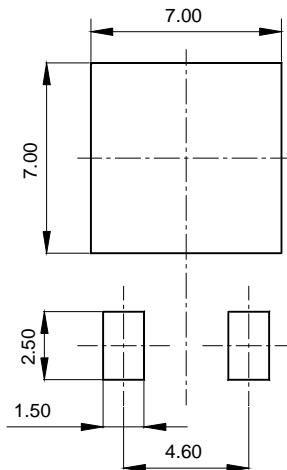


## Package Outline Dimensions (Unit: mm)



SYMBOL	MILLIMETERS			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
D	6.40	6.60	6.80	
D1	5.14	5.34	5.54	
E	0.50	0.70	0.90	
E1	5.90	6.10	6.30	
E2	0.50 TYP			
A	2.20	2.30	2.40	
A1	0.87	1.07	1.27	
C	0.40	0.50	0.60	
C1	0.40	0.50	0.60	
C2	2.10	2.30	2.50	
L	2.50	2.70	2.90	
L3	0.60	0.80	1.00	
b	0.66	0.76	0.86	
b1	0.96 MAX			
e	2.10	2.30	2.50	
F	0.80 MIN			
H	0.00	-	0.10	

## Recommended Land Pattern (Unit: mm)



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